

SiC Cascode in 440 VAC - 800 VDC Power Factor Correction

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Abstract

Until recently, the selection for switching devices in 440 VAC applications has been rather limited. The choice was typically between an IGBT or a large, high gate capacitance MOSFET. This power switch selection tended to limit switching frequencies to less than 50 kHz., which then required larger, more expensive inductors to maintain good power factor. With the introduction of wide bandgap switching devices, good efficiencies at higher switching frequencies become attainable, while producing more cost effective solutions by lowering the required inductance. This paper will explore the design tradeoffs for efficiency and power factor in implementing designs at higher frequencies (>75 kHz). For simplicity, only a single phase will be analyzed.

1.0 Power Factor Correction

This paper will focus on hard switched PFC's, as shown in their simplified form in Figure 1. The current through the boost inductor is PWM'd to mirror the input Voltage (Figure 2). This process makes the converter appear as a resistive load (PFC=1), and thus reducing line harmonics, which is the goal of this power stage. It is therefore important that when evaluating PFC's, one must always consider Power Factor in the context of efficiency.

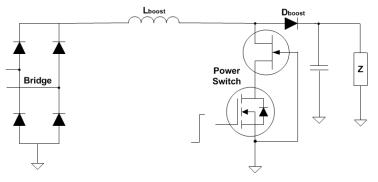


Figure 1: Basic Power Factor Correction Topology

Efficiency and Power Factor Correction

The common elements between Power Factor, efficiency and switching frequency are the power switch/boost diode pair and the inductor. An increase in frequency lowers the required inductance, which produces a smaller, cheaper inductor. The tradeoff with this is the obvious drop in efficiency due to the increased number of cycles. The goal is to find the correct tradeoff that generates the optimum power factor and efficiency at the right cost point.

M Pos: 0.000s CH1 Tek Coupling DC Off Coarse 10X Voltage Off CH2 500V M 2,50ms CH3 / 2,40mV 5A/di 26-Jan-16 15:39 60.0093Hz

Figure 2: Vin = 440VAC, Iin = 3.8A, PF = 0.993, fs = 100 kHz

2.0 Boost Inductor

Equation 1 is the required boost inductance for

continuous current mode (CCM) operation in a power factor correction converter. Figure 3 is the plot of this inductance with respect to switching frequency for a 440VAC input and an output power of 1.65kW. The inductor ripple current is set at 20% of the peak current (Note: There are many resources on the web with respect to PFC design, this paper will primarily rely on TI's UCC3818 datasheet, as it is PWM controller used in the test board).



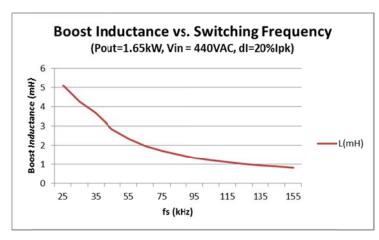
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1) Lboost(fs) :=
$$\frac{\text{Vin} \cdot \sqrt{2} \cdot D}{\text{dl fs}}$$

From the graph, the inductance can swing from 5.1 mH to 0.86 mH depending on frequency. The inductance value with respect to current required for the application will have a direct relationship to the cost of the inductor.

As an example, using the Magnetics Inc. software, and standardizing on the 55438 MPP core, a 25 kHz design, a 5.6 mH inductor requires 3 cores and 112 turns of 18 AWG, where a 150 kHz design, a 0.56 mH requires a single core 51 turns and there is room to use 14 AWG wire.

From a magnetics perspective it is clear that that moving to higher frequency / lower inductance one can produce a lower cost, more efficient inductor.



3.0 Switching FrequencyFigure 3: Boost Inductor vs. Switching Frequency

The inductance calculations highlight the advantages of increasing switching frequency, but the other side of the equation is that switching losses will be going up with frequency. A PFC test board (Figure 5) based on the UCC3818 current average controller was

designed along the same criteria as the previous example: 440 to 480 VAC input, 800 VDC output with an output power of 1.65 kW($^{\sim}$ 5 kW in a three phase system). The initial design will be for a lower switching frequency converter, and then higher frequency will be investigated. Note: 1.65 kW was chosen as it still allows for stepping up 440 VAC from a standard 110 VAC line.



The Power Switch and Boost Diodes are the UJC1210K Cascode (1.2 kV, 100 mOhm max). The advantage of the UJC1210K is not only its fast switching capability, but that it can also be driven with standard gate drive. Its performance capability allows it to compete



Figure 4: MPP Cores, 55438

economically against silicon solutions. Note: all test results shown in this paper will use a V_{GS} drive of 0 to 14 Volts.

Figure 5: UCC3818 PFC Test Board

An USCi Silicon Carbide Diode, UJ2D1205T (1.2 kV, 5 A) with a Q_C of 14 nC will be the boost diode. Once the $R_{G\ L}$ and $R_{G\ H}$ are

fixed, the only variables in the data will be the switching frequency, and the inductor design. A complete list of components can be found in the appendix. A Mathcad file based on Texas Instruments calculation is available upon request. This by no means a fully optimized design, but it is meant to highlight the relative tradeoffs between inductance and switching frequency with respect to efficiency and power factor.



4.0 Optimizing Gate Drive

As the UJC1210K is a cascode device, it is recommended to use the drive configuration shown in Figure 6. This allows control of the turn on and turn off behavior. As silicon carbide is inherently faster than silicon, and it is recommended to start with higher Rg values than silicon. In cascode, the $R_{\rm g_L}$ will typically be higher than the $R_{\rm g_H}$ value. It is recommended to start with an $R_{\rm g_H}$ of 10 Ohms and an $R_{\rm g_L}$ of 20 Ohms. These values can be swept +/- with selection determined by efficiency and EMI considerations.

In figure 7, such a process was undergone. A switching frequency of 130 kHz was chosen to accentuate the performance differences. An $R_{\rm g_H}$ at 7.5 Ohm and an $R_{\rm g_L}$ of 15 Ohms were determined to give acceptable results.

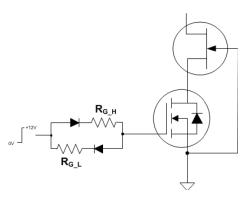
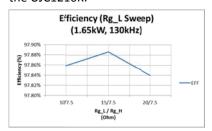
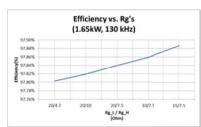


Figure 6: Cascode Rg_H and Rg_L Configuration

In Figure 8, the corresponding waveforms associated with these Rg values are shown. All waveforms appear well controlled with minimal ringing. An R_{g_H} of 7.5 Ohm and an R_{g_L} of 15 Ohms will be used in all measurements with the UJC1210K.





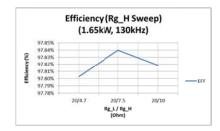
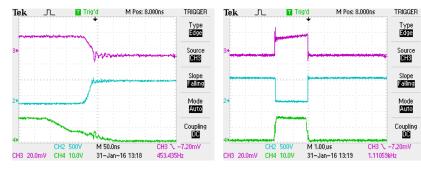


Figure 7: Rg_H and Rg_L Selection



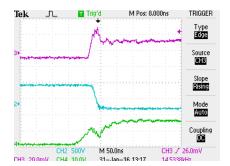


Figure 8: Turn Off, Full Period and Turn On (Rg_H=7.5 Ohm, Rg_L=15 Ohm)

5.0 Baseline Efficiency Curve

An Inductor was designed to generate good power factor down to switching frequency of 25 kHz. This curve will be used as a baseline to compare results against future optimizations, especially at higher frequencies. The inductor was wound using three 55438 MPP cores with 87 turns of 18 AWG, (3.9mH at the 1.65kW output power), which meets the criteria set in the graph of figure 1.



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For measurement purposes, the input power and power factor are measured using a Tektronix PA 1000 Power

Analyzer. The output power and 14V Controller/Driver Supply power are measured using Keysight 34465A 6.5 digit multi-meters. The lab power supply and the AC input power are added together for input power when calculating efficiency.

In figure 9 the UJC1210K efficiency curve is plotted with respect to switching frequency and power factor. As calculated, the power factor is well above 0.990 across all load and switching frequency conditions.

Per the data, the efficiency of the silicon carbide UJC1210K cascode (V $_{GS}$: 0 to 12 V) from 25 kHz to 150 kHz (98.55% @ 25 kHz / 97.87% @ 150 kHz) has a delta of 0.68%.

For a reference, this curve is compared against a similarly rated 900V super junction silicon MOSFET. The delta between efficiency across the same frequency spread is 1.19 percent. The efficiency delta grows between the two curves due switching losses as well as gate drive loss. A 6.9 Ohm gate resistor is used with the Silicon MOSFET, as compared to the 7.5 / 15 Ohm combination on the cascode.

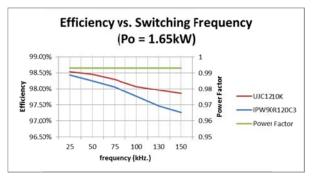


Figure 9: Efficiency vs. Switching Frequency

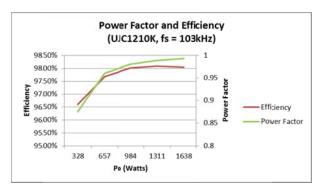


Figure 10: Efficiency vs. Load

Translating the efficiency comparison into actual loss, the cascode "loss delta" by increasing switching frequency from 25kHz to 150 kHz is 11.6 Watts, where the 900V, switching optimized MOSFET dissipates almost twice that amount at 20.3 Watts. By not dissipating the power in the first place, the SiC solution lowers the system thermal budget, and opens up the opportunity for higher switching frequency and lower inductor values.

In figure 10, the frequency is fixed at 103 kHz, and the load is swept from 328 Watts to 1.6 kW. It is noted that power factor with the given inductor begins to significantly roll off at 66% of load. The good news in this is that the peaks of the harmonics will also be dropping with power, so it is still possible to meet the line harmonic regulations with such a curve.

6.0 Lowering the Cost

In the previous example, the inductor was designed for low frequency operation (3.9 mH), and it still delivered reasonable results at 100 kHz and higher, but the goal in going to high frequency operation is to lower system cost with minimal impact to efficiency. A second inductor was designed to be optimized for 100 kHz operation, and only a single core (55438 MPP) is used. This design requires 68 turns of 14 AWG wire, to produce 1 mH inductance at load, which generates an inductor cost that is 30% of the previous example.

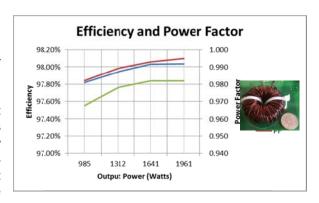


Figure 11: Boost Inductor (1 mH, 55438 MPP)

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Per figure 11, the efficiency at 100 kHz exceeds 98% with an inductor 1/3 the size of the previous design. The power level is approaching 2 kW, which translates to 6 kW in a 3 phase system.

7.0 Conclusion

This design is not the final answer on how high the efficiency can be produced at 100 kHz. These examples are to illustrate that one can take a low frequency design with standard drive (0 to 14V), and by substituting a silicon carbide device (UJC1210K), and increasing the switching frequency >> 75 kHz, one can reduce the inductor cost down to 30% of a low frequency design and still produce efficiency performance in excess of 98% and power factor ≥ 99.0%

8.0 Parts List

| Item | Designator | QTY | Value | Description | Manufacturer | Manufacturer # |
|----------|------------------------------------------|-----|---------|----------------------------------|-----------------------------------------------|---------------------------------------|
| 1 | C1, C8 | . 2 | 220pF | CAP CER 220PF 50V NP0 1206 | AVX Corporation | 12065A221JAT2A |
| 2 | C36, C37, C5, C7 | 4 | 1UF | CAP CER 1UF 25V 10% X7R 1206 | AVX Corporation | 12063C105KAT2A |
| 3 | C38 | 1 | 47UF | CAP CER 47UF 25V 20% X5R 1206 | TDK Corporation | C3216X5R1E476M160AC |
| 4 | C4 | 1 | 10000PF | CAP CER 10000PF 50V 10% X7R 1206 | AVX Corporation | 12065C103KAT2A |
| 5 | C6 | 1 | 3.9uF | C1206C395K3PACTU | KEMET | CGA5L1X7R1E685K160AC |
| 6 | C3, C39, C50, C42 | 4 | 0.1UF | CAP CER 0.1UF 50V 10% X7R 1206 | AVX Corporation | 12065C104KAT2A |
| 9 | C60, C11, C34, C35, C32, C33 | 6 | 0.15UF | CAP CER 0.15UF 1KV 10% X7R 2225 | KEMET | C2225C154KDRACTU |
| 10 | C9 | | 820pF | CAP CER 820PF 50V X7R 1206 | Yageo | 0040001/D\/TD0DD004 |
| 10 11 | C9 C12A, C12B, | 1 2 | , | CAP FILM 50UF 5% 900VDC RAD 4LD | Vishay | CC1206KRX7R9BB821 MKP1848C65090JY5 |
| 12 | C12A, C12B, | 1 | | CAP CER 2000PF 50V NP0 1206 | AVX Corporation | 12065A202JAT2A |
| 13 | C20 | 1 | | CAP TANT 47UF 25V 10% 2917 | AVX Corporation | TAJY476K025RNJ |
| 14 | C24, 25 | 2 | | CAP FILM 1UF 10% 1KVDC RADIAL | KEMET | R76QW4100SE30K |
| | · | _ | | RES SMD 27K OHM 1% 1/4W 1206 | | RMCF1206FT27K0 |
| 15 | R1 | 1 | | | Stackpole Electronics | RMCF1206FT27K0 |
| 16 | R8 | 1 | | RES SMD 20K OHM 1% 1/4W 1206 | Stackpole Electronics | |
| 17 | R5, R11, R9, R10 | 4 | | RES SMD 10K OHM 1% 1/4W 1206 | Panasonic | ERJ-8ENF1002V |
| 18 | R2A, R2B, R19A, R19B | 4 | | RES SMD 249K OHM 1% 1/4W 1206 | Panasonic | ERJ-8ENF2493V |
| 19 | R3 | 1 | 9.31K | RES SMD 9.53K OHM 1% 1/4W 1206 | Panasonic | ERJ-8ENF9311V |
| 20 | R4A, R4B, R2OA, R2OB | 4 | 267K | RES SMD 267K OHM 1% 1/4W 1206 | Panasonic | ERJ-8ENF2673V |
| 21 | R6 | 1 | | RES SMD 17.4K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT17K4 |
| 22 | R7 | 1 | | RES SMD 909K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT909K |
| 23 | R12 | 1 | | RES SMD 4.22K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT4K22 |
| 24 | R51 | 1 | | RES SMD 7.87K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT7K87 |
| 25 | R13A, R13B, R21A, R21B, R50A,B,C,D | 8 | 634k | RES SMD 634K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT634KCT-ND |
| 27 | R14 | 1 | 0.2 | RES SMD 0.2 OHM 1% 5W 4527 | Vishay Dale | WSR5R2000FEA |
| 28 | RG_H | 1 | 7.5 | RES SMD 7.5 OHM 1% 1/4W 1206 | Panasonic | ERJ-8RQF7R5V |
| 29 | RG_L | 1 | 15 | RES SMD 15 OHM 1% 1/4W 1206 | Panasonic | ERJ-8ENF15R0V |
| 30 | R40, R42 | 2 | 1k | RES SMD 1K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT1K00 |
| 31 | R41 | 1 | 100k | RES SMD 100K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT100K |
| 32 | R42 | 1 | 2.2k | RES SMD 2.2K OHM 1% 1/4W 1206 | Stackpole Electronics | RMCF1206FT2K20 |
| 33 | B1 | 1 | 60 | FERRITE CHIP 60 OHM 6000MA 1806 | Murata | BLM41PG600SN1L |
| 34 | T1, T3 | 2 | | TERM BLOCK 2POS SIDE ENTRY 10MM | TE Connectivity | 282858-2 |
| 35 | T2 | 1 | | CONN TERMINAL BLOCK 2POS 5.08MM | Molex | 395443002 |
| 36 | DH, DL, D5 | 3 | 40V | DIODE SCHOTTKY 40V 1A SOD123 | Diodes Incorporated | 1N5819HW-7-F |
| 37 | D7 | 1 | 1kV | DIODE GEN PURP 1KV 60A TO247AC | Vishay | VS-60APF10-M3 |
| 38 | D10 | 1 | 2.7 | DIODE ZENER 2.7V 500MW SOD123 | Diodes Incorporated | MMSZ5223B-7-F |
| 39 | U1 | 1 | | IC PFC CTRLR AVERAGE CURR 16SOIC | Texas Instruments | UCC3818D |
| 40 | U2 | 1 | | IC DRIVER MOSF 12A LO SIDE 8SOIC | Micrel | MIC4452YM TR |
| 41 | U3 | 1 | | IC COMP OTT R-R 44V TSOT-23-5 | Linear Technology | LT1716CS5#TRMPBF |
| 42 | F1 | 1 | | FUSE BLOK CARTRIDGE 500V 10A PCB | Schurter, Inc | 0031.8211 |
| 43 | BR1 | 1 | | RECT BRIDGE GPP 15A 800V GBJ | Micro Commercial Co | GBJ1508-BP |
| | AC1, AC2, CAI, CAOUT, CT, DRV, EN, | | | | | |
| | GND1,GND2,GND3,GND4, HV, HV_Return, IAC, | | | | Keystone | 1573-2 |
| 44 | MOUt, PKLMT, SS, VAOUT, VCC, VFF, Vsense | 21 | | TERMINAL TURRET DBL .082"L | | |
| 45 | L2 | 1 | | CHOKE COMM MODE W/HDR 1mH 10A | Bourns | 8108-RC |
| 46 | Q2 | 1 | | MOSFET N-CH 30V 1.8A MCPH3 | On Semiconductor | MCH3475-TL-E |
| 47 | HS1 | 1 | | FUSE BLOK CARTRIDGE 500V 10A PCB | Schurter, Inc | 0031.8201 |
| 48 | F1 - FUSE Cover | 1 | | Fuse Cover | Schurter, Inc | 853.0551 |
| 49 | L1 | 1 | | MPP Core (68Turns, 14 AWG) | Magnetics Inc | 55438 |
| 50 | Q1 | 1 | | 1.2kV, 45 mOhm Cascode | United silicon Carbide | UJC1210K |
| 51 | <u>Q1</u> D1 | 1 | | 1.2kV, 45 mOnm Cascode | United silicon Carbide United silicon Carbide | UJ2D1205T |



Note: Part numbers in red are for those wishing to use PCB for a 90/260 VAC to to 400 VDC, 1 kW PFC.

9.0 Schematic

